## **AMENDMENT**

Please amend the application, without prejudice, as follows:

## In the claims:

Insert the following new claims 10-14:

- 10. A method for forming an aluminide coating on a target surface of a metal substrate bounding a contained space of the substrate comprising:
  - a) positioning a coating tape over said contained space to at least partially enclose said contained space, wherein the coating tape is in out-of-contact relation with the target surface and comprises:
    - (1) a mixture comprising:
  - (i) at least one aluminum source comprising from about 90% to about 99% by weight of the mixture, the aluminum source containing from about 20 wt.% to about 60 wt.% aluminum; and
  - (ii) at least one halide activator comprising from about 1% to about 10% by weight of the mixture;
    - (2) at least one binder;
  - b) heating the target surface to a temperature effective to cause the aluminum source to react with the activator and the target surface, and thereby forming an aluminide coating on said target surface at least partially enclosing said contained space.
  - 11. The method of claim 10, wherein the aluminum source is a Cr—Al alloy containing from about 20 wt.% to about 60 wt.% Al in the alloy.
  - 12. The method of claim 11, wherein the halide activator is LiF.
  - 13. The method of claim 10, wherein the halide activator is LiF.
  - 14. The method of claim 10, further comprising the step of:

before positioning the coating tape, disposing a masking material onto an area of the metal substrate, said area being laterally adjacent to the contained space and not within the contained space, whereby the masking material inhibits the coating material from forming an aluminide coating on the laterally-adjacent area.

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